# Therma-Bridge™



0505 0510 0603 0605 0805 1005 1010 1020 1206 2010 2512 2525 3725

#### Electrically Isolated A&N Thermal Management Device

#### **Features**

- High thermal conductivity
- Multiple sizes and thicknesses
- Electrically isolated thermal connection
- Optimal control over board temperature
- RoHS PtAg or Solder coated
   PtAg terminals for easy attachment

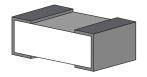
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COMPLIANT

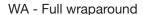
Part Number	Length Width		Height Option 'G'	Height Option 'T'	
0505	0.050"	0.050"	0.035" Max	N/A	
0510	0.050"	0.100"	0.035" Max	N/A	
0603	0.060"	0.030"	0.035" Max	N/A	
0805	0.080"	0.050"	0.035" Max	N/A	
1005	0.100"	0.050"	0.035" Max	N/A	
1206	0.126"	0.063"	0.035" Max	N/A	
1010	0.100"	0.100"	0.035" Max	0.050" Max	
1020	0.098"	0.197"	0.035" Max	0.050" Max	
2010	0.197"	0.098"	0.035" Max	0.050" Max	
2512	0.250"	0.120"	0.035" Max	0.050" Max	
2525	0.250"	0.250"	0.035" Max	0.050" Max	
3725	0.375"	0.250"	0.035" Max	0.050" Max	

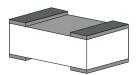
Choose the height option that best suits your thermal conductivity needs (see chart above) and build your Part Number below.

Additional sizes and thicknesses available upon request. Please contact factory. For detailed dimensional information, outline drawings are available from factory.

## **Terminal Style**





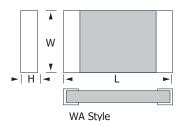


DS - Double sided

#### **Termination Materials**

- -3 PtAg (platinum silver) for epoxy or solder attachment
  - -C Sn62 solder coated PtAg for solder attachment
- P Sn96 solder coated PtAg for solder attachment

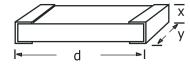
#### **Dimensional Outline**



The values are calculated using material constants, the area of each chip face  $(x \cdot y)$  and the thickness (d) of each device.

The thermal constant of A/N is:  $k\sim170\left(\frac{W}{m}^{\circ}C\right)$ 

Thermal resistance ( $\Theta$ R) is calculated as:  $\Theta_R = \frac{d}{kA} = \frac{d}{k(x \cdot y)}$ 



Normalized thermal conductivity is the reciprocal of thermal resistance.

Ordering Information Example: 1206 Size Therma-Bridge™ on 0.025" substrate with PtAg terminals							
B G 3	1206	WA					
Substrate Thickness		Style WA	os				
Termination Material - Sizes							
3 - PtAg	0505	0605	1010 <sup>1</sup>	25121	3725 <sup>1</sup>		
C - PtAg with Sn62 solder	0510	0805	1020 <sup>1</sup>	2010 <sup>1</sup>			
P - PtAg with Sn96 solder	0603	1005	1206	2525			

<sup>&</sup>lt;sup>1</sup> 0.040" Substrate available in size 1010 and larger

## International Manufacturing Services, Inc.

## **Application Example:**

Shared Mounting Pad with Heat Source

### **Applications Using Therma-Bridge™**

- RF Amplifiers
- Conduction Cooled Computers
- Power Supplies & Converters
- JTRS, MIDS-J, GMR, AMF
- Temperature Controlled Oscillators
- Lighting Ballasts
- Protecting Neighboring Components
- Conduction Cooled Handheld Devices

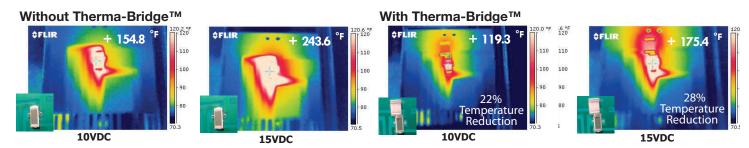
Heatsink

Therma-bridge™

- P25 Radios, Basestations & Repeaters
- Extracting Heat from Power FETS, LEDs, Pin & Laser Diodes

#### **Thermal Image Heat Transfer Demonstration**

Below is an actual test of the Therma-Bridge<sup>™</sup> showing a heat generating component mounted on an FR4 board. The images on the right show the temperature of the component being thermally aided by the Therma-Bridge<sup>™</sup> connected to a heat sink.



## **Thermal Conductivity & Electrical Capacitance**

The table below lists the thermal resistance (in black) given in degrees C per watt (°C/W), the equivalent thermal conductivity, normalized to chip size, (in red) given in milliwatts per degree C (mW/°C) and the electrical capacitance, (in blue) given in picofarads (pF) for each Therma-Bridge™ size and thickness combination.

These values are based on the nominal thermal resistance of Aluminum Nitride. Values are approximate.

		Nominal Therma-Bridge™ Thickness						
		0.025" Thickness "G"			0.040" Thickness "T"			
	0505	9°C/W	110mW/°C	0.15pF	N/A <sup>1</sup>	N/A <sup>1</sup>	N/A¹	
Φ	0510	4.6	215	0.3	N/A	N/A	N/A	
	0603	18	53	0.075	N/A	N/A	N/A	
Siz	0605	11	90	0.125	N/A	N/A	N/A	
Σ	0805	14	71	0.075	N/A	N/A	N/A	
-Bridge	1005	18	56	0.075	N/A	N/A	N/A	
	1206	19	53	0.075	N/A	N/A	N/A	
	1010	9	110	0.150	6°C/W	167mW/°C	0.24pF	
Therma	1020	4.5	210	0.3	3	330	0.48	
her	2010	19	53	0.075	12	83	0.12	
F	2512	19	53	0.075	12	83	0.12	
	2525	9	110	0.15	6	167	0.24	
	3725	14	71	0.1	9	110	0.16	